

# DB3S314J

## Silicon epitaxial planar type

For high speed switching circuits  
DB3J314J in SSMini3 type package

### ■ Features

- Short reverse recovery time  $t_{rr}$
- Small reverse current  $I_R$
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

### ■ Basic Part Number

Dual DB2J314 (Common anode)

### ■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Maximum peak reverse voltage	$V_{RM}$	30	V
Forward current	Single	30	mA
	Double *	20	
Peak forward current	Single	150	mA
	Double *	110	
Junction temperature	$T_j$	125	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +125	$^\circ\text{C}$

Note) \*: Value of each diode in double diodes used.

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

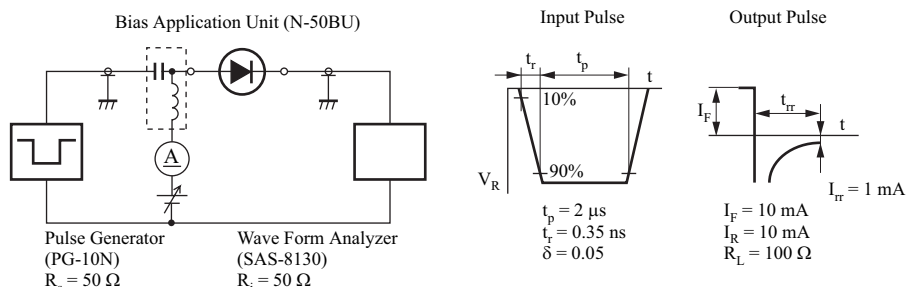
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_{F1}$	$I_F = 1 \text{ mA}$			0.4	V
	$V_{F2}$	$I_F = 30 \text{ mA}$			1.0	
Reverse current	$I_R$	$V_R = 30 \text{ V}$			300	nA
Terminal capacitance	$C_t$	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		1.5		pF
Reverse recovery time *	$t_{rr}$	$I_F = I_R = 10 \text{ mA}, I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$		1.0		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 2 GHz

\*:  $t_{rr}$  measurement circuit

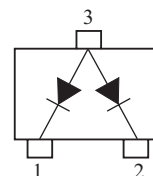


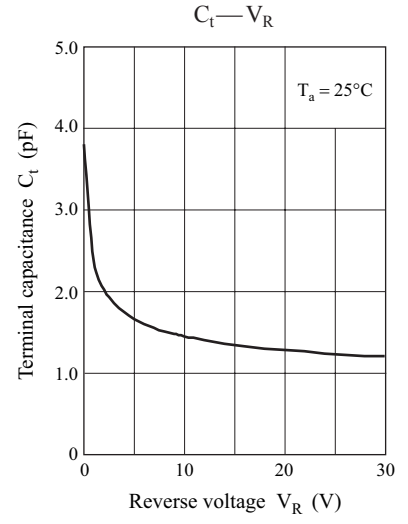
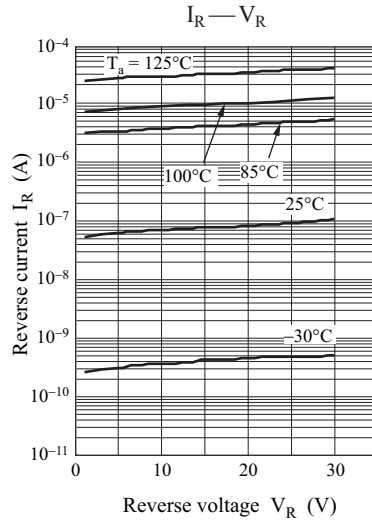
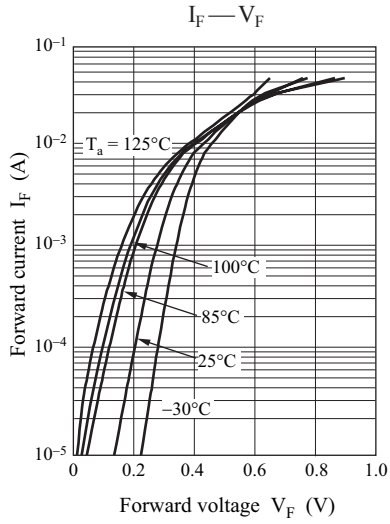
### ■ Package

- Code  
SSMini3-F3-B
- Pin Name  
1: Cathode-1                      3: Anode-1  
2: Cathode-2                      Anode-2

### ■ Marking Symbol: 4Y

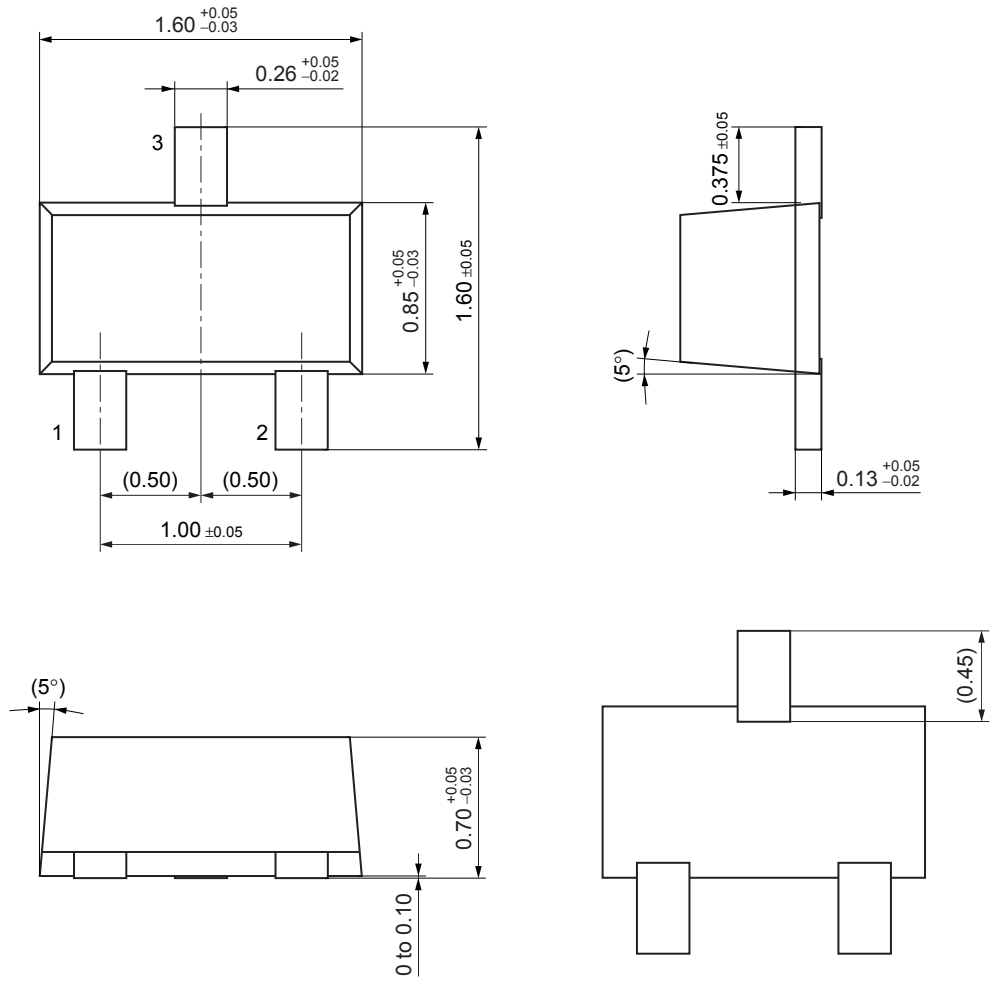
### ■ Internal Connection





SSMini3-F3-B

Unit: mm



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